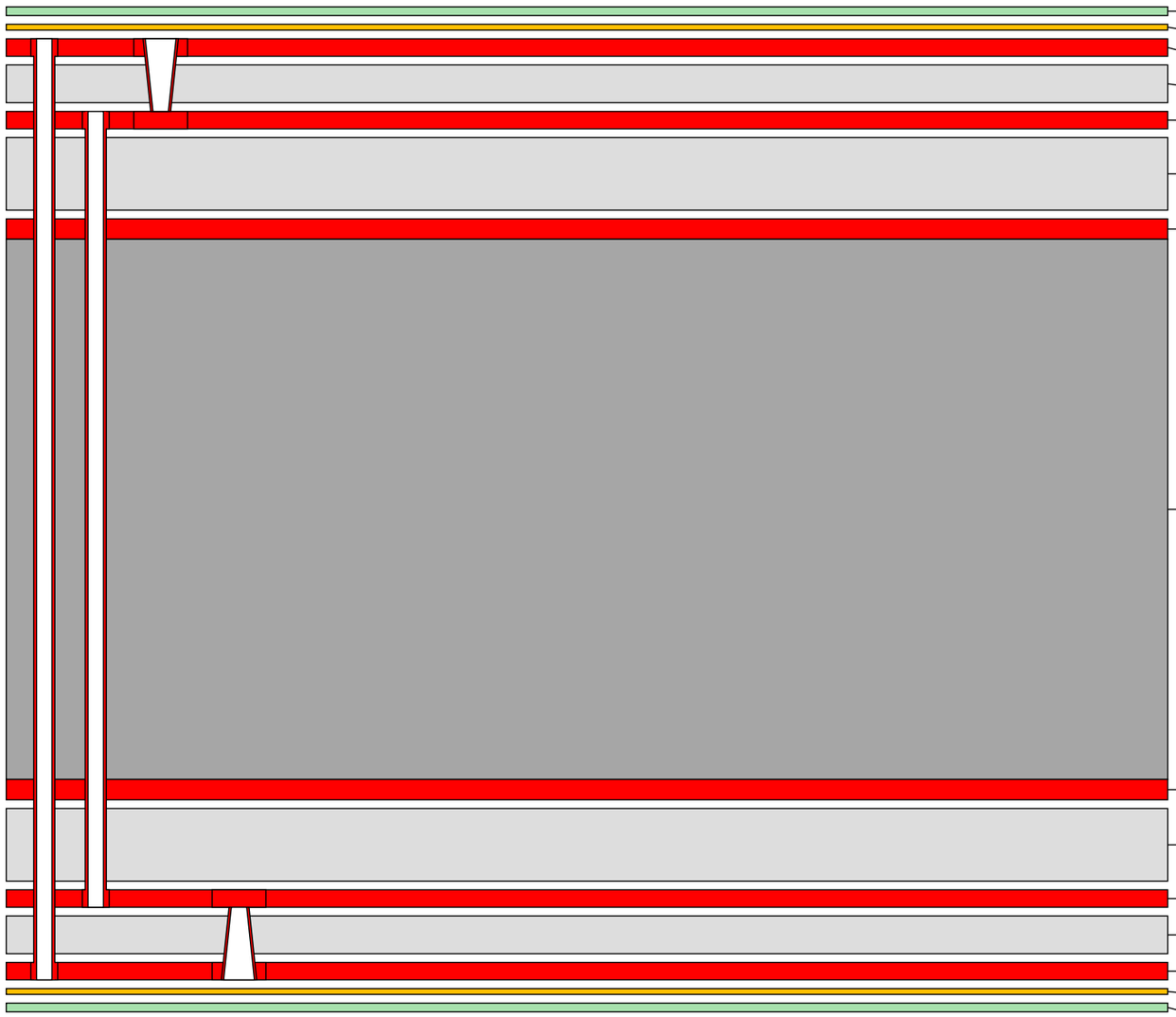

#	Layer	Thickness	Description	Note
	Top Solder	0.015mm	Soldermask IPC-SM840	used on rigid parts
	Top Surface Finish	0.006mm		
1	Top Side	0.030mm	Starting foil 1/4oz. after plating and processing	
		0.065mm	Prepreg IPC-4101/127/128	FR-4.1 filled, halogen free
2	Inner Layer 1	0.030mm	Starting foil 1/4oz. after plating and processing	
		0.125mm	Prepreg IPC-4101/127/128	FR-4.1 filled, halogen free
3	Inner Layer 2	0.035mm	ED Base Copper	
		0.930mm	Core IPC-4101/127/128	FR-4.1 filled, halogen free
4	Inner Layer 3	0.035mm	ED Base Copper	
		0.125mm	Prepreg IPC-4101/127/128	FR-4.1 filled, halogen free
5	Inner Layer 4	0.030mm	Starting foil 1/4oz. after plating and processing	
		0.065mm	Prepreg IPC-4101/127/128	FR-4.1 filled, halogen free
6	Bottom Side	0.030mm	Starting foil 1/4oz. after plating and processing	
	Bottom Surface Finish	0.006mm		
	Bottom Solder	0.015mm	Soldermask IPC-SM840	used on rigid parts

Total thickness: 1.541mm

notes:

Final copper thicknesses according to IPC-6012

Standard: Surface Finish ENIG
(Ni 5.5 µm ± 1.5 µm, Au 0.075 µm ± 0.025 µm)

Please follow our sectional design rules:
► www.we-online.com/designruleshdi_en

For impedance matching stackups: Please consult our specialists: HDI@we-online.com

HDI6_1-4b-1_154_35_2V13

PCB Thickness Tolerance: ± 10%

customer		created	
pcb name		approved	
engineer		format	A4, landscape
date			

Template Revision: 10/2023 by Andreas Schilpp / Michael Kress / Werner Öchslen

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